## **AMENDMENTS TO THE CLAIMS**

- 1. (Currently amended) An energy-curable coating composition comprising a water-soluble or water-dispersible binder capable of being polymerised by exposure to a source of radiation, a particulate electrically conductive material, and water as a non-reactive diluent, and, <u>if necessary optionally</u>, a photoinitiator, the composition, when cured, having a resistivity no greater than 1 ohm/square, as measured by ASTM F1896-98.
- 2. (Original) A composition according to Claim 1, in which the binder comprises at least a polymerisable monomer, prepolymer or oligomer capable of polymerisation by radiation and including at least one component which is water-soluble or water-dispersible.
- 3. (Currently amended) A composition according to Claim 2, in which the binder comprises a water-soluble or water-dispersible oligomer or prepolymer capable of being polymerised by radiation and/or a water-soluble monomer capable of being polymerised by radiation, or both and optionally a water-insoluble monomer capable of being polymerised by radiation.
- 4. (Original) A composition according to Claim 3, in which the binder comprises:
- (a) a water-soluble or water-dispersible oligomer or prepolymer capable of being polymerised by radiation,
  - (b) a water-soluble monomer capable of being polymerised by radiation,
  - (c) a water-insoluble monomer capable of being polymerised by radiation,
  - (d) a particulate electrically conductive material,

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(e) water as a solvent or dispersant, and

(f) optionally a photoinitiator.

5. (Currently amended) A composition according to any one of Claims 1 to 4 Claim 1, in which the binder comprises a water-soluble or water-dispersible urethane, polyester

or epoxy resin containing acrylate ester groups-and/or residues or both.

6. (Currently amended) A composition according to Claim 4, in which said water-soluble or water-dispersible oligomer or prepolymer (a) is a water-soluble or water-dispersible urethane, polyester or epoxy resin containing acrylate ester groups and/or

residues or both.

7. (Currently amended) A composition according to any one of Claims 1 to 6

Claim 1, in which the binder comprises an ester of acrylic or methacrylic acid with polyethylene glycol or with a mono-, di-, tri-, or tetra-hydric alcohol derived by ethoxylating a mono-, di-, tri-, or tetra-hydric alcohol of molecular weight less

than 200 with ethylene oxide.

8. (Original) A composition according to Claim 4, in which said water-soluble monomer (b) is an ester of acrylic or methacrylic acid with polyethylene glycol or with a mono-, di-, tri-, or tetra-hydric alcohol derived by ethoxylating a mono-, di-, tri-, or

tetra-hydric aliphatic alcohol of molecular weight less than 200 with ethylene oxide.

9. (Currently amended) A composition according to any one of Claims 1 to 8

Claim 1, in which the binder includes an acrylate or methacrylate ester of a mono-, di-, tri-, tetra-, penta-, or hexa-hydric alcohol preferably having a molecular weight of less

than 300.

10. (Original) A composition according to Claim 4, in which said water-insoluble

monomer (c) is an acrylate or methacrylate ester of a mono-, di-, tri-, tetra-, penta-, or

hexa-hydric alcohol preferably having a molecular weight of less than 300.

11. (Currently amended) A composition according to any one of the preceding

Claims Claim 1, in which said electrically conductive material is a metal or metal oxide.

12. (Original) A composition according to Claim 11, in which said metal is silver,

copper, nickel, tin, or platinum, or a mixture or alloy including at least one of these

metals.

13. (Currently amended) A composition according to any one of Claims 4,6, 8 and

10 Claim 4, in which said water-soluble or water-dispersible oligomer or prepolymer (a)

is present in an amount of from 2 to 15% by weight of the total composition.

14. (Currently amended) A composition according to any one of Claims 4,6, 8,10

and 13 Claim 4, in which said water-soluble monomer (b) is present in an amount of

from 2 to 10% by weight of the total composition.

15. (Currently amended) A composition according to any one of Claims 4,6, 8,10, 13

and 14 Claim 4, in which said water- insoluble monomer (c) is present in an amount of

from 1 to 8% by weight of the total composition.

16. (Currently amended) A composition according to any one of Claims 4,6, 8,10, 13

and 14 Claim 4, in which said conductive material (d) is present in an amount such that

the weight ratio of (d) to (a) plus (b) plus (c) is at least 2: 1.

17. (Original) A composition according to Claim 16, in which said ratio is at least 3:

1.

- 18. (Original) A composition according to Claim 17, in which said ratio is no greater than 6:1.
- 19. (Currently amended) A composition according to any one of the preceding Claims Claim 1, in which said conductive material is present in an amount of from 30 to 90% by weight of the total composition.
- 20. (Currently amended) A composition according to any one of Claims 1,2, 3,5, 7,9, 11 and 12 Claim 1, in which said conductive material is present in an amount of at least 35% by weight of the total composition.
- 21. (Original) A composition according to Claim 20, in which said conductive material is present in an amount of at least 40% by weight of the total composition.
- 22. (Currently amended) A composition according to any one of the preceding Claims Claim 1, in which said water is present in an amount of from 1 to 60% of the total composition.
- 23. (Original) A composition according to Claim 22, in which said water is present in an amount of from 1 to 40% of the total composition.
- 24. (Currently amended) A composition comprising:
- (a) from 2 to 15%, more preferably from 4 to 14%, by weight of a water-soluble or water-dispersible oligomer or prepolymer capable of being polymerised by radiation,
- (b) from 2 to 10%, more preferably from 2 to 9%, by weight of a water-soluble monomer capable of being polymerised by radiation,
- (c) from 1 to 8% by weight, more preferably from 3 to 7% by weight, of a water-insoluble monomer capable of being polymerised by radiation,

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- (d) sufficient of a particulate electrically conductive material that the ratio of said electrically conductive material to components (a), (b) and (c) is at least 2:1, preferably at least 3:1,
- (e) from 1 to 60%, more preferably from 1 to 40%, by weight of water as a non reactive diluent, and
- (f) optionally from 0.5 to 10%, more preferably from 1 to 5%, by weight of a photoinitiator, the composition, when cured, having a resistivity no greater than 1 ohm/square, as measured by ASTM F1896-98.
- 25. (Currently amended) A composition according to any one of the preceding Claims Claim 1, having, when cured, a resistivity no greater than 10-1 ohm/square, as measured by ASTM F1896-98.
- 26. (Currently amended) A composition according to any one of the preceding Claims Claim 25, having, when cured, a resistivity no greater than 10<sup>-2</sup> ohm/square, as measured by ASTM FI 896-98.
- 27. (Currently amended) A process for producing a printed electrically conductive coating, in which a composition according to any one of the preceding Claims Claim 1 is printed onto a substrate, and is then energy cured by exposure to a source of actinic radiation.
- 28. (Original) A process according to Claim 27, in which said radiation is ultraviolet or electron beam.
- 28. (New) A composition comprising:
- (a) from 4 to 14% by weight of a water-soluble or water-dispersible oligomer or prepolymer capable of being polymerised by radiation,

- (b) from 2 to 9%, by weight of a water-soluble monomer capable of being polymerised by radiation,
- (c) from 3 to 7% by weight of a water-insoluble monomer capable of being polymerised by radiation,
- (d) sufficient of a particulate electrically conductive material that the ratio of said electrically conductive material to components (a), (b) and (c) is at least 3:1
- (e) from 1 to 40% by weight of water as a non reactive diluent, and
- (f) from 1 to 5% by weight of a photoinitiator, the composition, when cured, having a resistivity no greater than  $10^{-2}$  ohm/square, as measured by ASTM F1896-98.